

Electrical Specifications (T_A=+25°C)

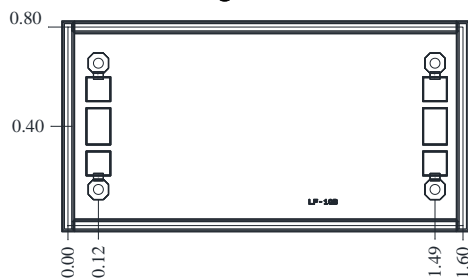
Parameter	Min.	Typ.	Max.	Unit
Cut-off Freq. (f ₀)	-	3	-	GHz
Insertion Loss @ f ₀	-	-	1.5	dB
Return Loss	21	-	-	dB
Out of band Attenuation	≥ 20@4.55GHz			dB
	≥ 40@5.1GHz			dB

Max. Input Power: 30dBm

Operating Temperature: -55°C~+125°C

Storage Temperature: -65°C~+150°C

Outline Drawing



Notes:

1. Dimensions are in millimeters. Tolerance: ±0.05 mm
2. Die thickness is 0.1 mm
3. Typical bond pad size is 0.1 x 0.1 mm

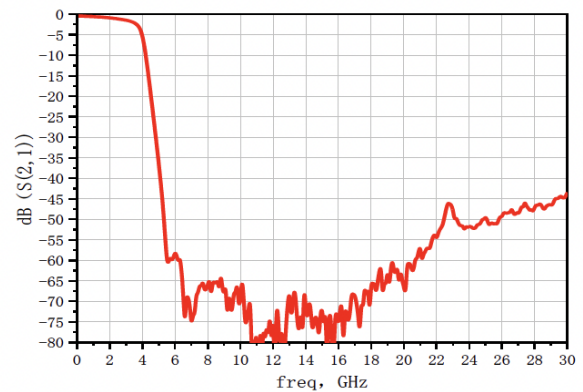
Recommended Assembly Diagram



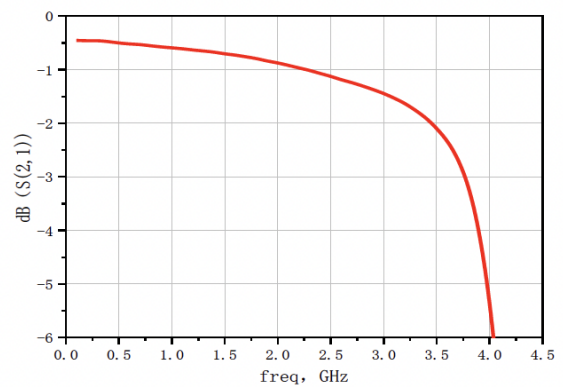
Notes:

1. Die is back-metallized and can be mounted with AuSn eutectic preform or with electrically conductive epoxy.
2. We recommend using Φ 25um Au wire for wire-bonding, with max wire length of 400um.
3. Sinter using AuSn (80/20) alloy, ensuring the temperature does not exceed 300°C for a maximum of 30 seconds.
4. Handle die in clean environment. Do not attempt to clean the chip using liquid cleaning systems.
5. Die is ESD sensitive. ESD protection is required during usage and storage.

Typical Wideband Insertion Loss at T_A=25



Typical Insertion Loss at T_A=25



Typical Return Loss at T_A=25

